

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	141	((cut\$4 or incision or groove or dic\$3 or split\$4 or separat\$3 or slit\$4 or trench) with ((first and second) with (substrate or wafer))) with semiconductor same ((terminal or bond) adj pad)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/01 10:38
L2	100	L1 not ("2007".ay. or "2006".ay. or "2005".ay. or "2004".ay.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/01 10:45
L3	3365	438/110.ccls. or 438/113.ccls. or 438/455.ccls. or 438/456.ccls. or 438/458.ccls. or 438/460.ccls. or 438/462.ccls.	USPAT	OR	ON	2007/10/01 10:45
L4	2879	L3 not ("2007".ay. or "2006".ay. or "2005".ay. or "2004".ay.)	USPAT	OR	ON	2007/10/01 10:45
L5	2879	L3 not ("2007".ay. or "2006".ay. or "2005".ay. or "2004".ay.)	USPAT	OR	ON	2007/10/01 10:53
L6	2163	L5 and ((first and second) with (surface or substrate or layer or wafer or base))	USPAT	OR	ON	2007/10/01 10:51
L7	1892	L6 and ((cut\$4 or incision or groove or dic\$3 or split\$4 or separat\$3 or slit\$4 or trench) with (surface or substrate or layer or wafer or base))	USPAT	OR	ON	2007/10/01 10:53
L8	93	257/E23.001 or 257/E21.499	USPAT	OR	ON	2007/10/01 10:54
L9	16	8 not ("2007".ay. or "2006".ay. or "2005".ay. or "2004".ay.)	USPAT	OR	ON	2007/10/01 10:53
L10	1169	257/E23.\$	USPAT	OR	ON	2007/10/01 10:56
L12	73	10 and (substrate with (saw\$3 oir dicing or diced))	USPAT	OR	ON	2007/10/01 10:56
L13	3092	257/E21.\$	USPAT	OR	ON	2007/10/01 10:56
L14	90	13 and (substrate with (saw\$3 oir dicing or diced))	USPAT	OR	ON	2007/10/01 10:56
L15	69	14 not 12	USPAT	OR	ON	2007/10/01 10:56
S1	3259	438/110.ccls. or 438/113.ccls. or 438/455.ccls. or 438/456.ccls. or 438/458.ccls. or 438/460.ccls. or 438/462.ccls.	USPAT	OR	ON	2007/06/07 17:48

## EAST Search History

S2	2861	S1 not ("2007".ay. or "2006".ay. or "2005".ay. or "2004".ay.)	USPAT	OR	ON	2007/10/01 10:45
S3	2150	S2 and ((first and second) with (surface or substrate or layer or wafer or base))	USPAT	OR	ON	2007/06/07 17:51
S4	1983	S3 and (cut\$4 or incision or groove or dic\$3 or split\$4 or separat\$3 or slit\$4 or trench)	USPAT	OR	ON	2007/06/07 17:52
S5	1879	S3 and ((cut\$4 or incision or groove or dic\$3 or split\$4 or separat\$3 or slit\$4 or trench) with (surface or substrate or layer or wafer or base))	USPAT	OR	ON	2007/10/01 10:51
S6	2	("6436793"   "6555901").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/06/07 18:25
S7	461	((cut\$4 or incision or groove or dic\$3 or split\$4 or separat\$3 or slit\$4 or trench) with ((first and second) with (substrate or wafer)) with semiconductor) and ((terminal or bond) adj pad)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/12 13:26
S8	313	S7 not ("2007".ay. or "2006".ay. or "2005".ay. or "2004".ay.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/12 13:29
S9	138	((cut\$4 or incision or groove or dic\$3 or split\$4 or separat\$3 or slit\$4 or trench) with ((first and second) with (substrate or wafer)) with semiconductor) same ((terminal or bond) adj pad)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/12 13:26
S10	98	S9 not ("2007".ay. or "2006".ay. or "2005".ay. or "2004".ay.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/01 10:38
S11	6	(("6787897") or ("6271102") or ("5459081") or ("5302554") or ("5128282") or ("4802952")).PN.	USPAT	OR	OFF	2007/06/12 15:12
S12	4	(("6555901") or ("5668033") or ("6407381") or ("5895233")).PN.	USPAT	OR	OFF	2007/06/12 15:13